

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ60P05
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight
Wafer	Silicon	7440-21-3	100.00%	0.2945%
Lead Frame	Cu	7440-50-8	97.025%	34.52%
	Fe	7439-89-6	2.211%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.079%	
	Zn	7440-66-6	0.015%	
	Ag	7440-22-4	0.66%	
Epoxy	Silver	7440-22-4	80.00%	0.4295%
	bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	12.00%	
	1,4-bis(2,3	2425-79-8	6.50%	
	dapsone	80-08-0	1.50%	
Wire	copper	7440-50-8	99.99%	0.2536%
	others	/	0.01%	
Mold Compound	Epoxy resin A	Trade Secret	5.91%	62.7986%
	Epoxy resin B	29690-82-2	3.87%	
	Phenol Resin	Trade Secret	2.20%	
	Silica(Amorphous) A	60676-86-0	80.51%	
	Silica(Amorphous) B	7631-86-9	6.88%	
	Carbon black	1333-86-4	0.63%	
Plating	Tin	7440-31-5	100.00%	1.7039%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.